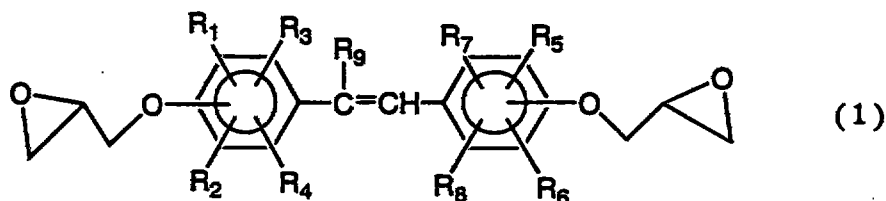


ABSTRACT OF THE DISCLOSURE

EPOXY RESIN COMPOSITION AND RESIN-ENCAPSULATED
SEMICONDUCTOR DEVICE

Provided is an epoxy resin composition comprising:

(A) an epoxy compound represented by the general formula
(1):



wherein, R_1 to R_8 represent each independently a hydrogen atom, an acyclic or cyclic alkyl group having 1 to 6 carbon atoms, a substituted or unsubstituted phenyl group or a halogen atom,

(B) a polyfunctional epoxy compound having a functional group number of two or more, and

(C) an epoxy curing agent containing a phenolic hydroxyl group,

wherein the proportion of the epoxy compound (A) is from 1 to 99% by weight based on the total weight of the epoxy compounds (A) and (B).

The epoxy resin composition has low moisture absorption and other properties in well-balanced particularly as a material for encapsulating electronic parts.

(No suitable figure)